



Material Content Data Sheet



Sales Product Name	TLE7824G			Issued		28. August 2013		
MA#	MA001101476							
Package	PG-DSO-28-38			Weight*		831.40 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	18.138	2.18	2.18	21817	21817
leadframe	inorganic material	phosphorus	7723-14-0	0.071	0.01		86	
	non noble metal	zinc	7440-66-6	0.285	0.03		343	
	non noble metal	iron	7439-89-6	5.709	0.69		6866	
	non noble metal	copper	7440-50-8	231.798	27.88	28.61	278804	286099
wire	noble metal	gold	7440-57-5	0.909	0.11	0.11	1093	1093
encapsulation	organic material	carbon black	1333-86-4	1.127	0.14		1356	
	plastics	epoxy resin	-	51.852	6.24		62367	
	inorganic material	silicondioxide	60676-86-0	510.626	61.41	67.79	614175	677898
leadfinish	non noble metal	tin	7440-31-5	4.913	0.59	0.59	5910	5910
plating	noble metal	silver	7440-22-4	1.403	0.17	0.17	1688	1688
glue	plastics	epoxy resin	-	1.142	0.14		1374	
	noble metal	silver	7440-22-4	3.426	0.41	0.55	4121	5495
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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